

AMENDMENTS TO THE CLAIMS:

1. (Original) A tape with a built-in IC chip used for a sheet with a built-in IC chip, comprising: a tape body; and an IC chip provided with the tape body, wherein a part or all of the IC chip is embedded in the tape body.
2. (Original) A tape with a built-in IC chip according to claim 1, wherein all of the IC chip is embedded in the tape body.
3. (Original) A tape with a built-in IC chip according to claim 2, wherein all of the IC chip is embedded in the tape body in a non-exposed state.
4. (Original) A tape with a built-in IC chip according to any one of claims 1-3, wherein the IC chip is fixed to the tape body by a resin.
5. (Currently amended) A tape with a built-in IC chip according to any one of claims ~~1-4~~ 1-3, wherein the tape body is formed by at least two layers of base materials.
6. (Currently amended) A sheet with a built-in IC chip, comprising: a sheet-like material; and a tape with a built-in IC chip according to any one of claims ~~1-5~~ 1-3 which is inserted into the sheet-like material.
7. (Original) A sheet with a built-in IC chip according to claim 6, wherein the tape with a built-in IC chip is embedded in the sheet-like material formed of multilayer paper.
8. (Currently amended) A sheet with a built-in IC chip according to claim 7, wherein at least a portion of a middle layer of the multilayer paper which corresponds to a position for embedding the IC chip is formed without attaching a sheet of raw material to the portion or discontinuously attaching the sheet of raw material.

9. (Original) A sheet with a built-in IC chip according to claim 6, wherein a part of the tape with a built-in IC chip is in an exposed state.

10. (Currently amended) A sheet with a built-in IC chip, comprising: a sheet-like material; and a tape with a built-in IC chip according to any one of claims ~~4-5~~ 1-3 which is attached to the sheet-like material.